

15 April 2004

10/026,176

L Number	Hits	Search Text	DB	Time stamp
-	2028	205/118,122,123,125.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/14 12:02
-	143	205/118,122,123,125.ccls. and barrier and seed	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:00
-	5096	427/96,98,99.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/14 13:17
-	4766	29/25.01,25.02,25.03.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/14 13:18
-	75	(205/118,122,123,125.ccls. and barrier and seed) and (photoresist or resist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/14 13:24
-	28	(205/118,122,123,125.ccls. 427/96,98,99.ccls. 29/25.01,25.02,25.03.ccls.) and barrier and (seed with photoresist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/14 13:32
-	2	6355153.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/14 13:44
-	77	(205/118,122,123,125.ccls. 427/96,98,99.ccls. 29/25.01,25.02,25.03.ccls.) and seed and barrier and photoresist	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/14 13:45
-	58	205/118,122,123,125.ccls. and barrier and seed and ((copper adj (sulphate or sulfate)) or (cupric adj salt))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:01
-	11766	205/118,122,123,125.ccls. 427/96,98,99.ccls. 29/25.01,25.02,25.03.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:05

-	198	(205/118,122,123,125.ccls. 427/96,98,99.ccls. 29/25.01,25.02,25.03.ccls.) and (copper and electroless\$4 and hypophosphite)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:06
-	120	(205/118,122,123,125.ccls. 427/96,98,99.ccls. 29/25.01,25.02,25.03.ccls.) and (copper and electroless\$4 and hypophosphite and electroplat\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:07
-	81	(205/118,122,123,125.ccls. 427/96,98,99.ccls. 29/25.01,25.02,25.03.ccls.) and (copper and electroless\$4 and electroplat\$6) and (hypophosphite with reduc\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:18
-	14	(205/118,122,123,125.ccls. 427/96,98,99.ccls. 29/25.01,25.02,25.03.ccls.) and ((CoWP or CoPW or CoPl or NiPl or NiWP! or NiPW! or CoB! or NiB! or CoWB! or CoBW!) with electroless\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 14:02
-	4	((205/118,122,123,125.ccls. 427/96,98,99.ccls. 29/25.01,25.02,25.03.ccls.) and ((CoWP or CoPW or CoPl or NiPl or NiWP! or NiPW! or CoB! or NiB! or CoWB! or CoBW!) with electroless\$4)) and hypophosphite	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 10:40
-	2	6015482.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 11:01
-	6	((("4810332") or ("6159845") or ("5695810"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 11:01
-	36	4810332.URPN.	USPAT	2004/04/15 11:02
-	0	(205/118,122,123,125.ccls. 427/96,98,99.ccls. 29/25.01,25.02,25.03.ccls.) and ((CoWP or CoPW or CoPl or NiPl or NiWP! or NiPW! or CoB! or NiB! or CoWB! or CoBW!) with (PVD or CVD or (vapor adj deposition)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 14:03
-	5	((CoWP or CoPW or CoPl or NiPl or NiWP! or NiPW! or CoB! or NiB! or CoWB! or CoBW!) with barrier with (PVD or CVD or (vapor adj deposition)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/15 14:03